

Supplier Name: Texas Instruments Inc. (DUNS# 00-732-1904)  
 Contact Info: [ti.com/support](http://ti.com/support)  
 Form/Declaration Type: Distribute - RoHS and IEC 62474 DB  
 Created on: 05/30/2022

Details for "ISO7830FDWW"

**Current Product Information**

TI part number	Lead finish/Ball material	MSL rating/peak reflow	Assembly site	Package   Pins	Package body size (mm)	Total device mass (mg)*
ISO7830FDWW	NIPDAU	Level-2-260C-1 YEAR	TI TAIWAN A/T	DWW   16	14x10.3x2.65	1085.9

\*Total Device Mass  
 The summary mass is a rounded value and will be within approximately +/- 10% of the detailed mass value.

**Environmental Ratings Information**

RoHS	REACH	Green	IEC 62474 DB
Yes	Yes	Yes	Yes

**Component Information**

Component	Substance	CAS Number	Amount (mg)	Homogeneous Material Level		Component Level	
				Percentage %	ppm	Percentage %	ppm
<b>Bond Wire</b>							
Copper and Its Alloys	Iron	7439-89-6	0.00001	0.000208	2	0	0
Other Nonferrous Metals and Alloys	Calcium	7440-70-2	0.00001	0.000208	2	0	0
Other Nonferrous Metals and Alloys	Yttrium	7440-65-5	0.00003	0.000624	6	0	0
Precious Metals	Gold	7440-57-5	0.48046	99.997919	999979	0.044245	442
Precious Metals	Silver	7440-22-4	0.00005	0.001041	10	0	0
Sub-Total			0.48047	100	1000000	0.044246	442
<b>Die Attach Adhesive</b>							
Precious Metals	Silver	7440-22-4	0.289894	75.000065	750001	0.026696	267
Thermoplastics	Epoxy	85954-11-6	0.096631	24.999935	249999	0.008899	89
Sub-Total			0.386525	100	1000000	0.035595	356
<b>Die Attach Adhesive 2</b>							
Precious Metals	Silver	7440-22-4	0.289894	75.000065	750001	0.026696	267
Thermoplastics	Epoxy	85954-11-6	0.096631	24.999935	249999	0.008899	89
Sub-Total			0.386525	100	1000000	0.035595	356
<b>Lead Frame</b>							
Copper and Its Alloys	Copper	7440-50-8	373.958883	97.05	970500	34.437353	344374
Copper and Its Alloys	Iron	7439-89-6	10.018476	2.6	26000	0.922588	9226
Copper and Its Alloys	Phosphorus	7723-14-0	0.577989	0.15	1500	0.053226	532
Zinc and Its Alloys	Zinc	7440-66-6	0.770652	0.2	2000	0.070968	710
Sub-Total			385.326	100	1000000	35.484135	354841
<b>Lead Frame Plating</b>							
Nickel and Its Alloys	Nickel	7440-02-0	1.274608	95.12	951200	0.117377	1174
Precious Metals	Gold	7440-57-5	0.010452	0.78	7800	0.000963	10
Precious Metals	Palladium	7440-05-3	0.05494	4.1	41000	0.005059	51
Sub-Total			1.34	100	1000000	0.123399	1234
<b>Mold Compound</b>							
Other Inorganic Materials	Fused Silica	60676-86-0	621.100131	89.5	895000	57.196246	571962
Other Organic Materials	Chlorine	7782-50-5	0.013879	0.002	20	0.001278	13
Other Plastics and Rubber	Carbon Black	1333-86-4	3.469833	0.5	5000	0.319532	3195
Thermoplastics	Epoxy	85954-11-6	69.382783	9.998	99980	6.389364	63894
Sub-Total			693.96626	100	1000000	63.90642	639064
<b>Semiconductor Device</b>							
Ceramics / Glass	Doped Silicon	7440-21-3	2.012252	100	1000000	0.185305	1853
Sub-Total			2.012252	100	1000000	0.185305	1853
<b>Semiconductor Device 2</b>							
Ceramics / Glass	Doped Silicon	7440-21-3	2.012252	100	1000000	0.185305	1853
Sub-Total			2.012252	100	1000000	0.185305	1853
<b>Total</b>			1085.91065			100	1000000

**Important Note**  
 The ppm calculations are at the homogeneous material level and are maximum concentration values. The ppm displayed represents the homogeneous material with the highest ppm for that substance. The amount (mg) calculations represent the maximum total amount of each substance within the component.  
 The ppm calculations are at the component level and are average concentration values. The amount (mg) calculations represent the average total amount of each substance within the component.  
[See Glossary of Terms for more details.](#)

**Important Part Information**  
 There is a remote possibility the Customer Part Number (CPN) your company uses could reference more than one TI part number. This is due to two or more users (EMSI's or subcontractors) using the same CPN for different TI part numbers. If this occurs, please check your Customer Part Number and cross reference it with the TI part number seen on this page.

**Product Content Methodology**  
[For an explanation of the methods used to determine material weights, See Product Content Methodology](#)

**Material Declaration Certificate for Semiconductor IC Packaged Products**

TI certifies that the material content information provided by TI is representative and accurate to the best of their knowledge based on material information provided by its suppliers and their combination into finished IC packaged products. TI semiconductor products designated to be "Pb-free", "Green" or "RoHS Exempt" fully meets the latest EU RoHS Directive requirements along with other legislation as seen in the former JIG-101 list that has been transferred to the IEC 62474 database.

**Important Information/Disclaimer**  
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Signature: [\(click here for a fuller statement with a signed certificate\)](#)

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 For further environmental statements, please go to [www.ti.com/ecoinfo](http://www.ti.com/ecoinfo)  
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**RoHS:** Means TI semiconductor products that are compliant with the current RoHS requirement that the maximum concentration values of the ten substances listed in RoHS Annex II do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI semiconductor products labeled as "RoHS Compliant" are suitable for use in specified lead-free processes. TI may also reference these types of semiconductor products as "Pb-Free." These TI semiconductor products are also fully compliant with GADSL and the IEC 62474 database for electronic requirements.

**RoHS Exempt:** Means TI semiconductor products that contain lead (Pb) above the RoHS Annex II threshold, but that fall within one of the specific RoHS exemptions noted above or documented in <http://www.ti.com/lit/pdf/szzq088>

**Green:** Means the content of Chlorine (Cl) and Bromine (Br)-based flame retardants meet J5709B low halogen requirements of <=1 000ppm threshold; Antimony trioxide (Sb2O3) contained in halogen based flame retardant materials meets the <=1 000ppm threshold requirement; and Beryllium Oxide (BeO) is <=1000ppm.